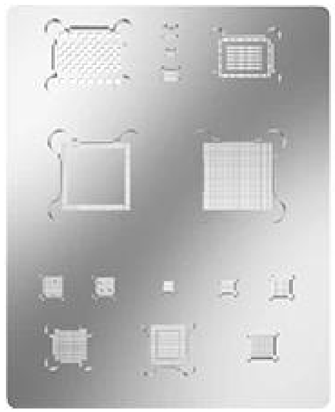
BEST-A9-High Quality Universal BGA IC Chip Stencils Heated Template Reballing Stencil for iphone 6 6P

1x BGA Reballing Stencils for iPhone 6s Plus
1x BGA Reballing Stencils for iPhone 6s

Product Usage



MODEL	A9
WEIGHT	18.8g
MATERIAL	imported steel
SIZE	68.9 X 84.9mm
MATCHING MACHINE TYPE	iPhone6S/6SPlus

▼ CHARACTERISTICS

This product is used for BGA tinning repair of the iPhone 6S/6sPlus series. Imported steel, anti-rolling anti-deformation, automatic alignment, accurate hole position, non-stick tin, good toughness, good off-grid.

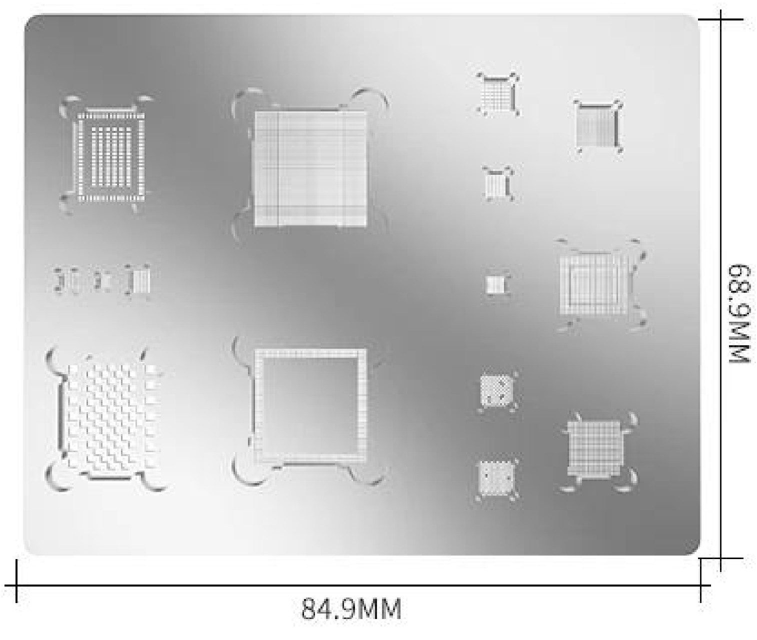
PRODUCT INFORMATION

Easily mounted on the steel mesh to make the chip fit more closely with the mesh

Therefore, the chip after tinning is "more precise"

Imported steel
Hard and wear resistant
Accurate to the hole

PRODUCT SIZE



Thin to 0.31mm

Precise die-casting Iform heating